

## **EPOXY RESINS AND VARNISHES LEAD FREE SOLDER RESIST\***

REF	COMMENTS	CURING SCHEDULE	VISCOSITY	RESISTIVITY	THERMAL CONDUCTIBILITY	MAIN USE
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### **ELECTRICALLY CONDUCTIVE EPOXY RESINS, LEAD FREE SOLDER RESIST**

<b>E212LF</b>	Two-component, Pot life 2 days, Easy to dispense	from 80°C to 200°C	25 Pa.S	<0,3 mΩ.cm	---	Tantalum capacitors
<b>E213LF</b>	One-component, Pot life 2 days, Easy to dispense	from 75°C to 200°C	25 Pa.S	<0,3 mΩ.cm	2,5-3 W/(m.°K)	Tantalum capacitors
<b>E216LF</b>	One-component, Pot life 5 days, Easy to dispense	from 150°C to 200°C	15 Pa.S	<0,3 mΩ.cm	---	Electrical connections
<b>E217LF</b>	One-component, Pot life 5 days, Easy to dispense	from 150°C to 200°C	12,5 Pa.S	<1 mΩ.cm	2-2,5 W/(m.°K)	large size chip bonding

### **ELECTRICALLY CONDUCTIVE VARNISHES, LEAD FREE SOLDER RESIST**

<b>V402LF</b>	One-component, Storage stability 3 months at T° < -10°C, Flexible	from 150°C to 180°C	10 Pa.S	0,2 mΩ.cm	---	End termination surface mounting components
<b>V403LF</b>	One-component, Storage stability 9 months at T° < -5°C, Flexible	from 150°C to 180°C	3,7 Pa.S	<0,3 mΩ.cm	---	End termination surface mounting components
<b>V404LF</b>	One-component, Storage stability 3 months at T° < -10°C, Flexible	from 150°C to 180°C	10 Pa.S	0,2 mΩ.cm	---	End termination surface mounting components

### **THERMALLY CONDUCTIVE EPOXY RESINS, LEAD FREE SOLDER RESIST**

<b>E703LF</b>	One-component, Pot life 1 week, Low volatile	from 75°C to 140°C	10 Pa.S	---	1 W/(m.°K)	Chip bonding
<b>E704LF</b>	One-component, Pot life 1 week, Low volatile	from 75°C to 140°C	7,5 Pa.S	---	0,7 W/(m.°K)	Chip bonding
<b>E707- 2 LF</b>	One-component, Storage stability 3 months at 20°C, Very reactive	from 125°C to 200°C	12 Pa.S	---	1-1,5 W/(m.°K)	Strain jauges bonding

The information in this sheet is based on data measurements which we believe to be correct. Epotecny, however, does not accept responsibility for the adaptation of this product to any particular use.

\* for more precision on the technical properties, to refer to the individual data sheet.

Maj 24/01/2007